Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.7X1.4 & 2.7X0.95 EP)
Lead Count	24
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.14E-02	83.25	832500	41.79	417874
Thermosets	Epoxy resin	Proprietary	1.40E-03	5.42	54200	2.72	27206
Thermosets	Phenol resin	Proprietary	8.89E-04	3.45	34500	1.73	17317
Other inorganic materials	Metal Hydroxide	Proprietary	1.40E-03	5.42	54200	2.72	27206
Others	Others	Proprietary	6.34E-04	2.46	24600	1.23	12348
Subtotal			2.58E-02	100.00	1000000	50.20	501951

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.93 E-02	97.50	975000	37.63	376294
Copper & its alloys	Iron	7439-89-6	4.65 E-04	2.35	23500	0.91	9070
Copper & its alloys	Zinc	7440-66-6	2.38 E-05	0.12	1200	0.05	463
Copper & its alloys	Phosphorus	7723-14-0	5.94 E-06	0.03	300	0.01	116
Subtotal			1.98 E-02	100.00	1000000	38.59	385942

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	7.96 E-05	90.9	909091	0.16	1551
Precious metals	Palladium	7440-05-3	5.97 E-06	6.8	68182	0.01	116
Precious metals	Gold	7440-57-5	1.99 E-06	2.3	22727	0.00	39
Subtotal			8.75 E-05	100.00	1000000	0.17	1706

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	6.97 E-04	100.0	1000000	1.36	13577

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.81 E-03	100.0	1000000	9.38	93776

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.20 E-04	77.00	770000	0.23	2348
Other organic materials	Acrylic resin	Proprietary	1.10 E-05	7.00	70000	0.02	213
Other organic materials	Acrylate	Proprietary	8.61 E-06	5.50	55000	0.02	168
Other organic materials	Polybutadiene derivative	Proprietary	7.04 E-06	4.50	45000	0.01	137
Thermoset	Epoxy resin	Proprietary	3.91 E-06	2.50	25000	0.01	76
Other organic materials	Butadiene Copolymer	Proprietary	2.35 E-06	1.50	15000	0.00	46
Others	Additive	Proprietary	2.35 E-06	1.50	15000	0.00	46
Others	Peroxide	Proprietary	7.82 E-07	0.50	5000	0.00	15
Subtotal			1.56 E-04	100.0	1000000	0.30	3049

	Weight (g)	Percentage (%)	PPM
Package Totals	**5.13 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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